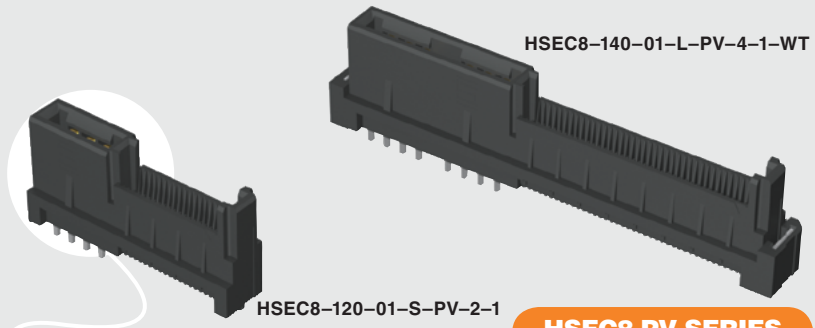
samtec

10 YEAR MFG WITH 30 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES



(0.80 mm) .0315"

HSEC8-PV SERIES

POWER/HIGH-SPEED EDGE CARD COMBO

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-PV

Insulator Material:
Black Liquid Crystal Polymer
Signal Contact:
BeCu
Power Contact:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp:
-55 °C to +125 °C
Current Rating:
Signal Pin: 3.2 A per pin
(2 pins powered)
Power Pin: 27.5 A per pin
(2 pins powered)
RoHS Compliant:
Yes

PROCESSING

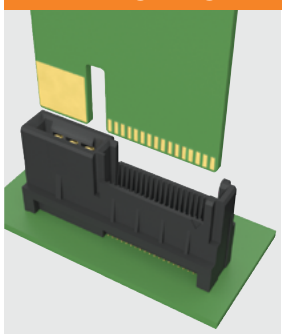
Lead-Free Solderable:
Yes

RECOGNITIONS

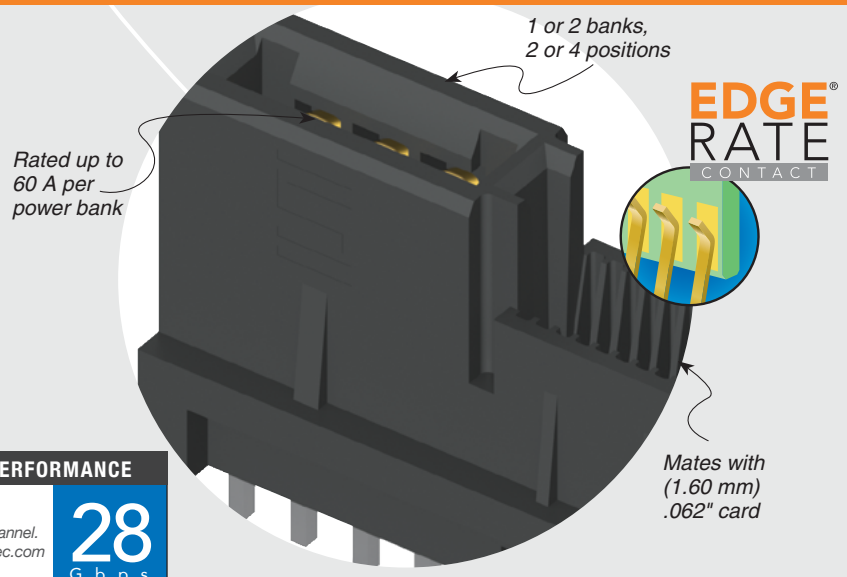
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

APPLICATION



Mates with:
(1.60 mm) .062" thick card



HIGH-SPEED CHANNEL PERFORMANCE

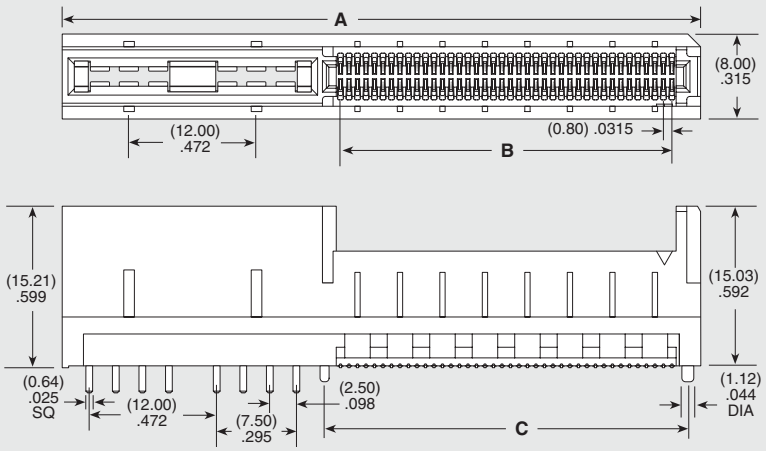
HSEC8-PV

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

28 Gbps

HSEC8	1	SIG POS	CARD THICKNESS	PLATING OPTION	PV	PWR POS	POWER TAIL	OTHER OPTION
		20, 30, 40 (Signal positions per row)	–01 = (1.60 mm) .062" Thick Card	–L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail –S = 30 µ" (0.76 µm) Gold on contact, Matte Tin on tail		–2, –4 (Total, 2 per power bank)	1 = Use with (1.60 mm) .062" Thick PCB –2 = Use with (2.36 mm) .093" Thick PCB	–WT = Weld Tab

SIGNAL POSITIONS	POWER POSITIONS					
	A (–2)	B (–2)	C (–2)	A (–4)	B (–4)	C (–4)
–20	(32.10) 1.264	(15.20) .598	(18.20) .717	(44.10) 1.736	(15.20) .598	(18.20) .717
–30	(40.10) 1.579	(23.20) .913	(26.20) 1.031	(52.10) 2.051	(23.20) .913	(26.20) 1.031
–40	(48.10) 1.894	(31.20) 1.228	(34.20) 1.346	(60.10) 2.366	(31.20) 1.228	(34.20) 1.346



POWER TAIL	D
–1	(2.35) .093
–2	(3.13) .123

Note:
Some lengths, styles and options are non-standard, non-returnable.